

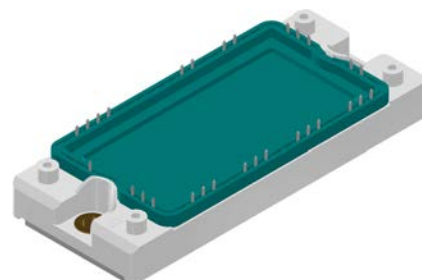
High Voltage Standard Rectifier Module

3~ Rectifier	Brake Chopper
$V_{RRM} = 2200 \text{ V}$	$V_{CES} = 1700 \text{ V}$
$I_{DAV} = 210 \text{ A}$	$I_{C25} = 145 \text{ A}$
$I_{FSM} = 1000 \text{ A}$	$V_{CE(sat)} = 1,8 \text{ V}$

3~ Rectifier Bridge + Brake Unit + NTC

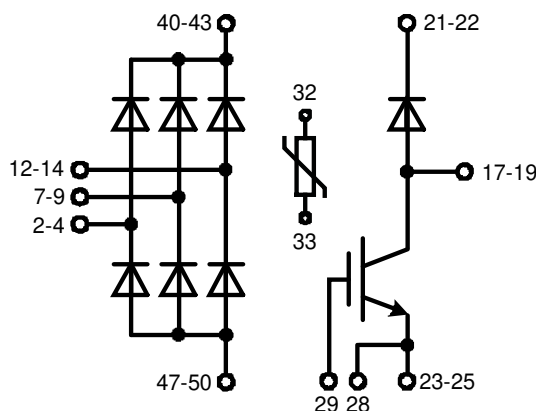
Part number

MDNA210UB2200TED



Backside: isolated

 E72873



Features / Advantages:

- Brake with Infineon IGBT³

Applications:

- 3~ Rectifier with brake unit for drive inverters

Package: E2-Pack

- Isolation Voltage: 4300 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Height: 17 mm
- Base plate: Copper internally DCB isolated
- Advanced power cycling
- Phase Change Material available

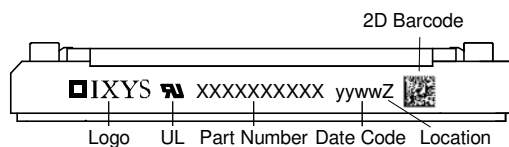
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Rectifier				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V_{RSM}	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^{\circ}\text{C}$				2300	V
V_{RRM}	max. repetitive reverse blocking voltage	$T_{VJ} = 25^{\circ}\text{C}$				2200	V
I_R	reverse current	$V_R = 2200\text{ V}$	$T_{VJ} = 25^{\circ}\text{C}$			100	μA
		$V_R = 2200\text{ V}$	$T_{VJ} = 150^{\circ}\text{C}$			2	mA
V_F	forward voltage drop	$I_F = 70\text{ A}$	$T_{VJ} = 25^{\circ}\text{C}$			1,23	V
		$I_F = 210\text{ A}$				1,75	V
		$I_F = 70\text{ A}$	$T_{VJ} = 125^{\circ}\text{C}$			1,19	V
		$I_F = 210\text{ A}$				1,67	V
I_{DAV}	bridge output current	$T_C = 85^{\circ}\text{C}$ rectangular $d = \frac{1}{3}$	$T_{VJ} = 150^{\circ}\text{C}$			210	A
V_{F0}	threshold voltage	} for power loss calculation only		$T_{VJ} = 150^{\circ}\text{C}$		0,82	V
r_F	slope resistance					5,2	m Ω
R_{thJC}	thermal resistance junction to case					0,5	K/W
R_{thCH}	thermal resistance case to heatsink				0,1		K/W
P_{tot}	total power dissipation	$T_C = 25^{\circ}\text{C}$				250	W
I_{FSM}	max. forward surge current	$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 45^{\circ}\text{C}$			1,00	kA
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$			1,08	kA
		$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 150^{\circ}\text{C}$			850	A
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$			920	A
I^2t	value for fusing	$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 45^{\circ}\text{C}$			5,00	kA ² s
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$			4,85	kA ² s
		$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 150^{\circ}\text{C}$			3,62	kA ² s
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$			3,52	kA ² s
C_J	junction capacitance	$V_R = 400\text{ V}; f = 1\text{ MHz}$			33		pF

Brake IGBT + Diode				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V_{CES}	collector emitter voltage	$T_{VJ} = 25^{\circ}\text{C}$				1700	V
V_{GES}	max. DC gate voltage					± 20	V
V_{GEM}	max. transient gate emitter voltage					± 30	V
I_{C25}	collector current	$T_C = 25^{\circ}\text{C}$				145	A
I_{C80}		$T_C = 80^{\circ}\text{C}$				100	A
P_{tot}	total power dissipation	$T_C = 25^{\circ}\text{C}$				540	W
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 75\text{ A}; V_{GE} = 15\text{ V}$	$T_{VJ} = 25^{\circ}\text{C}$		1,8	2,16	V
			$T_{VJ} = 125^{\circ}\text{C}$		2,1		V
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 4\text{ mA}; V_{GE} = V_{CE}$	$T_{VJ} = 25^{\circ}\text{C}$	5,2	5,8	6,4	V
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0\text{ V}$	$T_{VJ} = 25^{\circ}\text{C}$			0,1	mA
			$T_{VJ} = 125^{\circ}\text{C}$		0,7		mA
I_{GES}	gate emitter leakage current	$V_{GE} = \pm 20\text{ V}$				500	nA
$Q_{G(on)}$	total gate charge	$V_{CE} = 900\text{ V}; V_{GE} = 15\text{ V}; I_C = 75\text{ A}$			1200		nC
$t_{d(on)}$	turn-on delay time	inductive load $V_{CE} = 900\text{ V}; I_C = 75\text{ A}$ $V_{GE} = \pm 15\text{ V}; R_G = 3,9\ \Omega$	$T_{VJ} = 125^{\circ}\text{C}$		320		ns
t_r	current rise time				50		ns
$t_{d(off)}$	turn-off delay time				550		ns
t_f	current fall time				400		ns
E_{on}	turn-on energy per pulse				15		mJ
E_{off}	turn-off energy per pulse				18		mJ
RBSOA	reverse bias safe operating area	$V_{GE} = \pm 15\text{ V}; R_G = 3,9\ \Omega$	$T_{VJ} = 125^{\circ}\text{C}$				
I_{CM}		$V_{CEK} = 1700\text{ V}$				200	A
SCSOA	short circuit safe operating area	$V_{CEK} = 1700\text{ V}$					
t_{SC}	short circuit duration	$V_{CE} = 900\text{ V}; V_{GE} = \pm 15$	$T_{VJ} = 125^{\circ}\text{C}$			10	μs
I_{SC}	short circuit current	$R_G = 3,9\ \Omega$; non-repetitive			400		A
R_{thJC}	thermal resistance junction to case					0,23	K/W
R_{thCH}	thermal resistance case to heatsink				0,08		K/W
Brake Diode							
V_{RRM}	max. repetitive reverse voltage		$T_{VJ} = 25^{\circ}\text{C}$			1700	V
I_{F25}	forward current		$T_C = 25^{\circ}\text{C}$			81	A
I_{F80}			$T_C = 80^{\circ}\text{C}$			54	A
V_F	forward voltage	$I_F = 60\text{ A}$	$T_{VJ} = 25^{\circ}\text{C}$			2,20	V
			$T_{VJ} = 125^{\circ}\text{C}$		2,00		V
I_R	reverse current	$V_R = V_{RRM}$	$T_{VJ} = 25^{\circ}\text{C}$			0,1	mA
			$T_{VJ} = 125^{\circ}\text{C}$			1,2	mA
Q_{rr}	reverse recovery charge	$V_R = 900\text{ V}$ $-di_F/dt = 1600\text{ A}/\mu\text{s}$ $I_F = 60\text{ A}; V_{GE} = 0\text{ V}$	$T_{VJ} = 125^{\circ}\text{C}$		15		μC
I_{RM}	max. reverse recovery current				100		A
t_{rr}	reverse recovery time				550		ns
E_{rec}	reverse recovery energy				6,5		mJ
R_{thJC}	thermal resistance junction to case					0,6	K/W
R_{thCH}	thermal resistance case to heatsink				0,2		K/W

Package E2-Pack				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
I _{RMS}	<i>RMS current</i>	per terminal			30	A	
T _{VJ}	<i>virtual junction temperature</i>		-40		150	°C	
T _{op}	<i>operation temperature</i>		-40		125	°C	
T _{stg}	<i>storage temperature</i>		-40		125	°C	
Weight				176		g	
M _D	<i>mounting torque</i>		3		6	Nm	
d _{Spp/App}	<i>creepage distance on surface striking distance through air</i>	<i>terminal to terminal</i>	6,0			mm	
d _{Spb/Apb}		<i>terminal to backside</i>	12,0			mm	
V _{ISOL}	<i>isolation voltage</i>	t = 1 second	4300			V	
		t = 1 minute	3600			V	
		50/60 Hz, RMS; I _{ISOL} ≤ 1 mA					



Part description

M = Module
 D = Diode
 N = High Voltage Standard Rectifier
 A = (>= 2000V)
 210 = Current Rating [A]
 UB = 3~ Rectifier Bridge + Brake Unit
 2200 = Reverse Voltage [V]
 T = Thermistor \ Temperature sensor
 ED = E2-Pack

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MDNA210UB2200TED	MDNA210UB2200TED	Box	6	526034

Temperature Sensor NTC

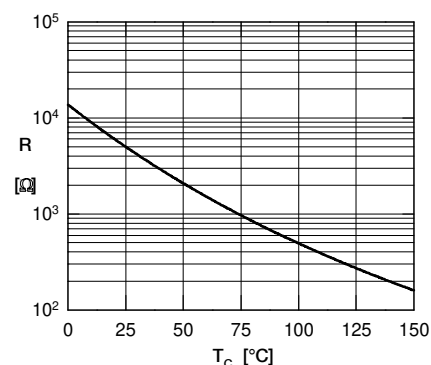
Symbol	Definition	Conditions	min.	typ.	max.	Unit
R_{25}	resistance	$T_{VJ} = 25^\circ$	4,85	5	5,15	kΩ
$B_{25/50}$	temperature coefficient			3375		K

Equivalent Circuits for Simulation

* on die level

$T_{VJ} = 150^\circ\text{C}$

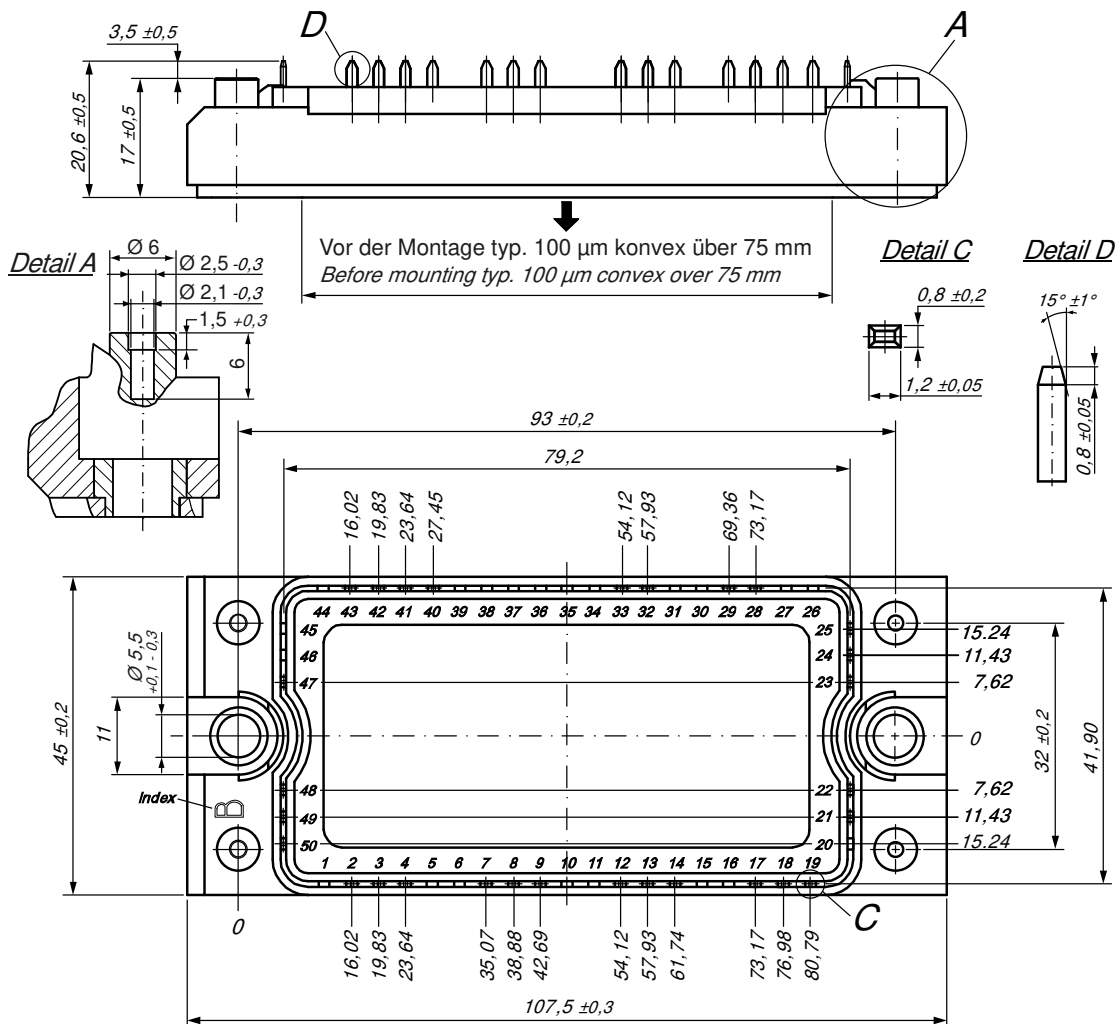
		Rectifier	Brake IGBT +	Brake Diode	
V_0	threshold voltage	0,82	1,1	1,22	V
R_0	slope resistance *	3,1	17,9	13	mΩ



Typ. NTC resistance vs. temperature



Outlines E2-Pack

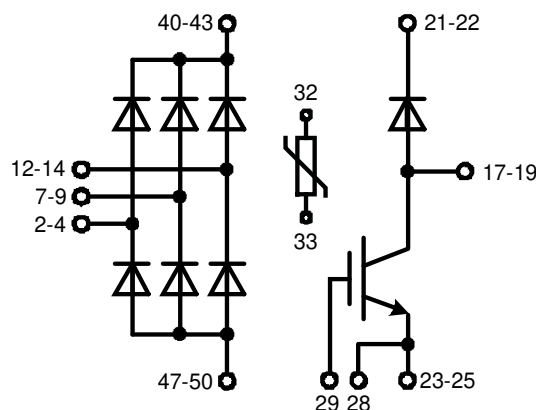


Bemerkung / Note:

- Nichttolerierte Maße nach / Measure without tolerances according DIN ISO 2768-T1-m
- PCB-Lochmuster / PCB hole pattern: **see pin position**
- Toleranz Pin-Position und PCB-Lochmuster / Tolerance of pin position and PCB hole pattern: $\pm 0,1$
- Montageanleitung / Mounting instruction: www.ixys.com **Application note IXAN0024**

Detail A: PCB-Montage / Mounting on PCB *

- Empfohlene, selbstschneidende Schraube / Recommended, self-tapping screw: **EJOT PT®** (Größe / size: **K25**)
- Max. Schraubenlänge / Max. screw length: **PCB-Dicke / thickness + 6 mm** (max. Lochtiefe / hole depth) *
- Empfohlenes Drehmoment / Recommended mounting torque: **1.5 Nm**



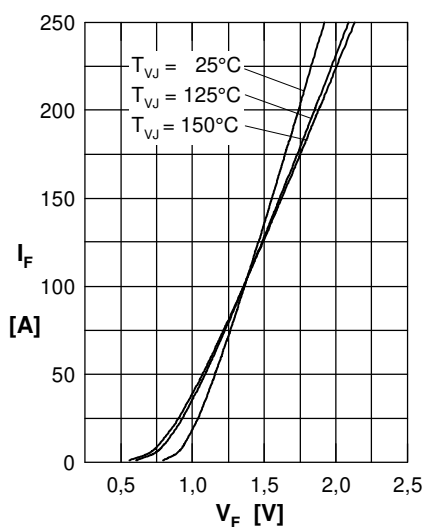
Rectifier


Fig. 1 Forward current versus voltage drop per diode

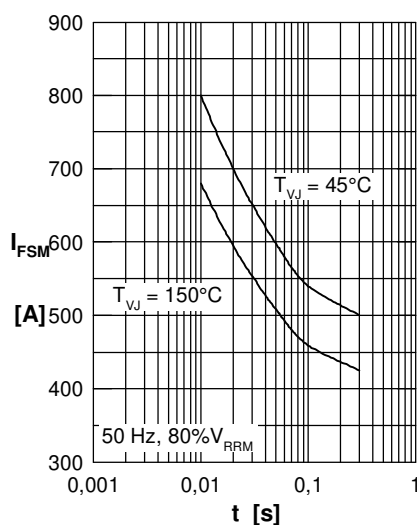


Fig. 2 Surge overload current vs. time per diode

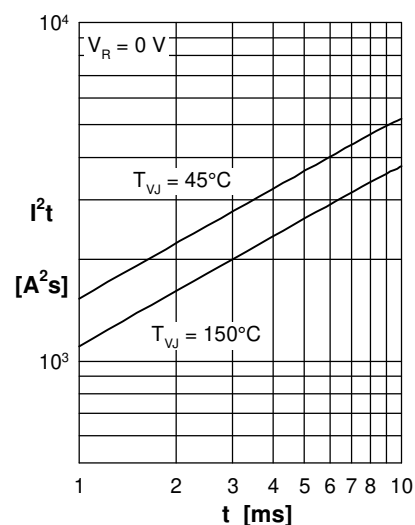
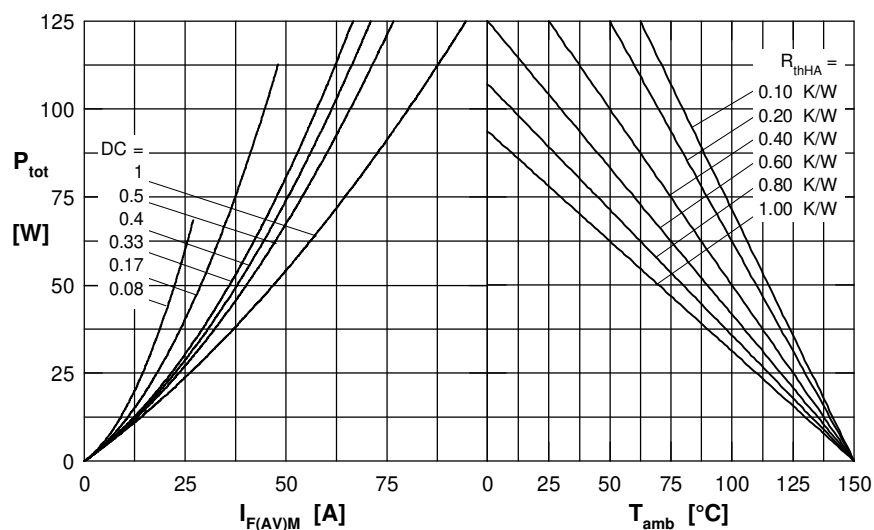

 Fig. 3 I^2t versus time per diode


Fig. 4 Power dissipation vs. forward current and ambient temperature per diode

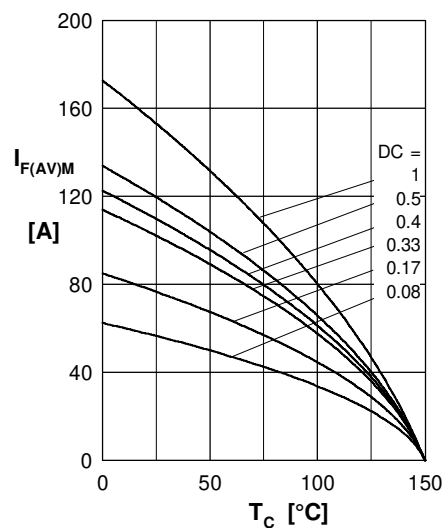


Fig. 5 Max. forward current vs. case temperature per diode

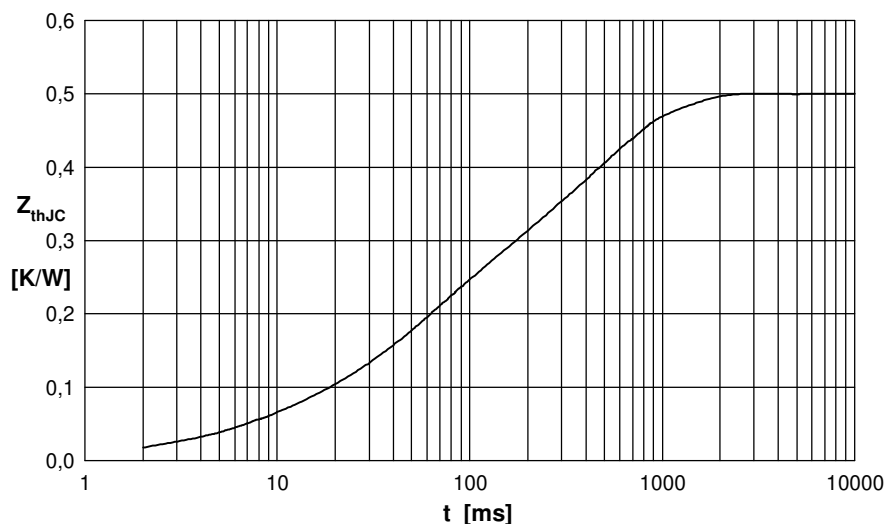


Fig. 6 Transient thermal impedance junction to case vs. time per diode

 Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.030	0.006
2	0.003	0.007
3	0.182	0.045
4	0.285	0.450

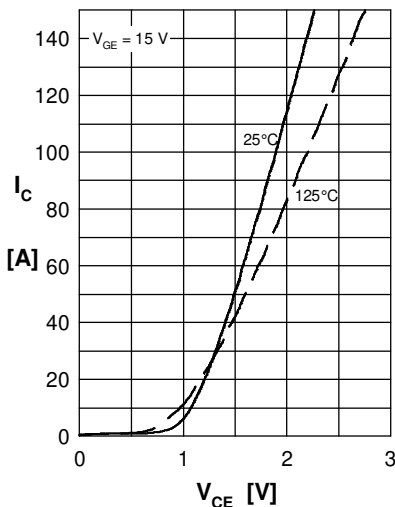
Brake IGBT + Diode


Fig.1 Output characteristics IGBT

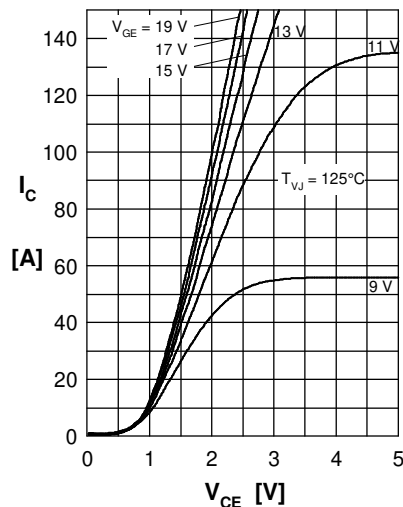


Fig.2 Typ. output characteristics IGBT

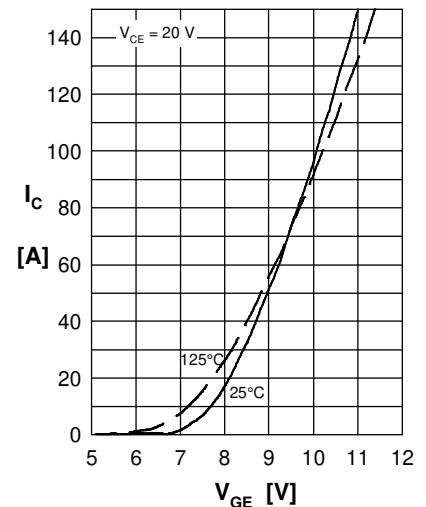


Fig.3 Typ. transfer charact. IGBT

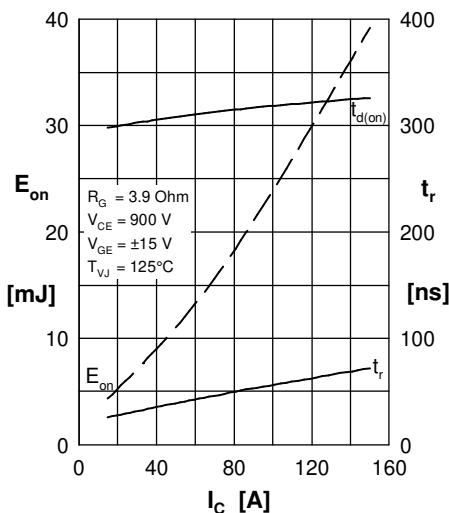


Fig.4 Typ. turn-on energy & switch. times vs. collector current

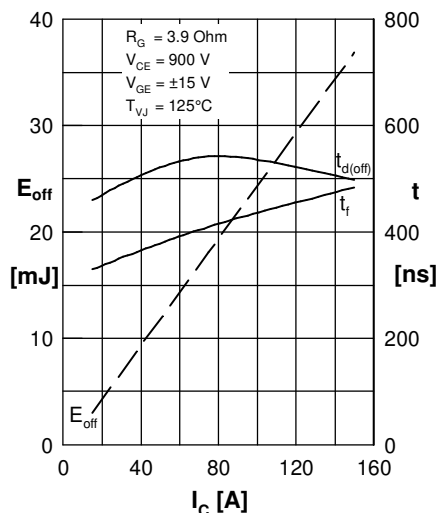


Fig.5 Typ. turn-off energy & switch. times vs. collector current

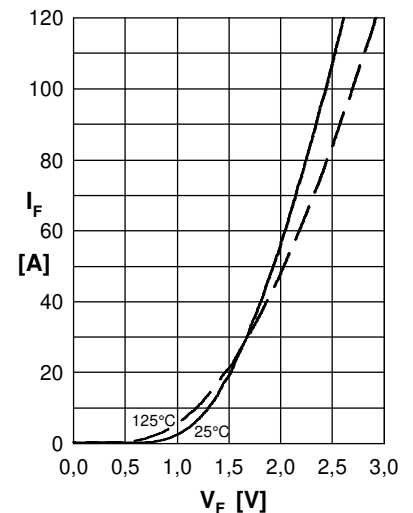


Fig.6 Typ. forward characteristics Diode

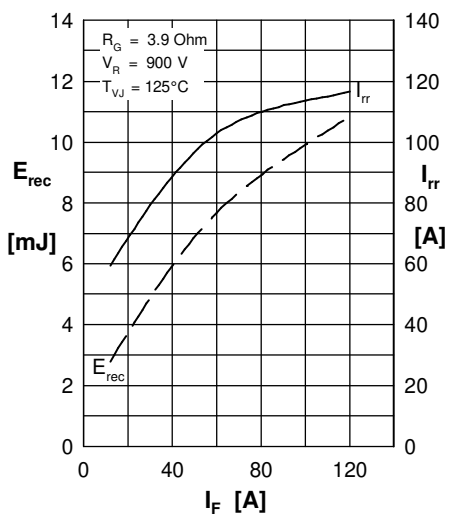


Fig.7 Typ. reverse recovery characteristics Diode

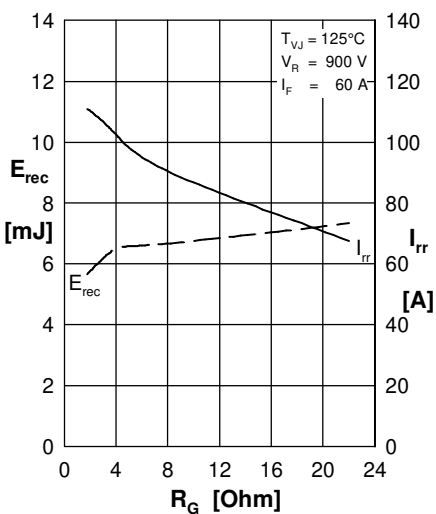


Fig.8 Typ. reverse recovery characteristics Diode

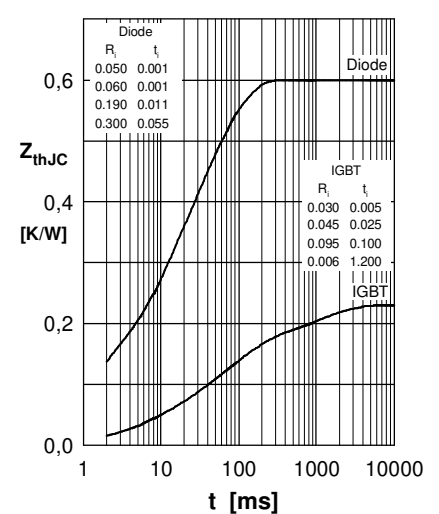


Fig.9 Transient thermal resistance junction to case